Return Material Authorization Guidelines

Disclaimer: Advanced Assembly stands behind its workmanship using the latest IPC standards and customer supplied documentation. We are committed to our customers and unconditionally warrant the workmanship free from assembly defects. Upon request, Advanced Assembly will review all documentation supplied (including BOM, XYRS and Gerber files) and internal record documentation (including BMB, readme, and HOLD resolution) to determine if a workmanship defect occurred.

Simply put, if Advanced Assembly made a mistake we will make it right.

AA is responsible: When all information needed (as shown above) for the assembly was clearly identified.

1. Instructions not followed: Any special instruction from the customer received in a timely manner about the assembly that has not been completed.
2. Missing parts : Parts that should be installed
3. Incorrect parts: Parts that do not match P/N provided
4. Incorrect rotation/polarity: Parts rotation that do not match to specification provided
5. Wrong location: Parts wrong side of PCB
6. Workmanship issues: Does not meet IPC standard class 2, or class 3 per customer requirements

Note: Corrective Action requests require detailed information (reference designator, defect, photograph) for proper analysis of root causes related to the problem. This may also require return of a PCB to Advanced Assembly for in depth testing and analysis for a complete investigation and corrective action completion.

AA is NOT responsible: When the conditions presented are not identified by information needed and cannot be determined by visual inspection or x-ray analysis.

1. Missing parts: Parts not in the XYRS files, customer BOM provided, or listed as DNI
2. Incorrect parts: Customer supplied parts do not match BOM
3. Incorrect rotation/polarity: Parts rotation matches XYRS provided
4. Wrong location: Parts placement that matches with XYRS provided
5. Workmanship issues: Parts that meet IPC standard class 2 or class 3 per customer requirements.
6. Functionality issues: Customers not providing assembly instructions to protect parts and boards from damage. Examples:
    a. Damaged parts: temperature, water sensitive, or parts with unique handling requirements where information is not provided identifying the special process needed
    b. Mixed technology RoHS parts processed using Non-RoHS (leaded) assembly process
    c. Customer Modified/Customized components
    d. Parts not received in manufacturer original packaging may require rework beyond the original quoted price for assembly
7. Bare board design issues:
    a. Wrong bare board revision due to incorrect Gerber files
    b. Insufficient/Missing solder due to existent via holes on pads
    c. Customer Supplied boards not environmentally controlled and packaged per IPC specifications.
8. Wiring/special processes/additional steps to build the assembly not provided by customer
9. IPC class 3 requirements not specified at the time of quote
10. Depanelization instructions for customer supplied boards not provided at the time of quote
11. Misaligned parts / Insufficient solder connection due to wrong size/design of pads for part layout
12. Design requirements that exceed the IPC installation guidelines without the tooling/fixture needed to meet the customer specific design element
13. Build with specific required standards, that are not specified at the time of quote
14. Latent failures due to environmental exposure or failure induced by stress testing beyond the design capabilities of the materials used